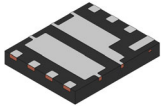
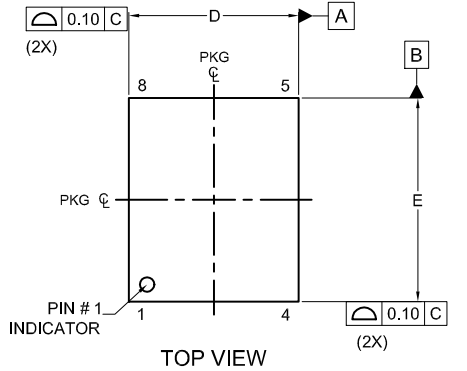


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

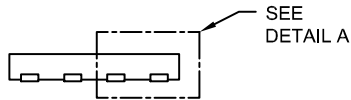


PQFN8 5X6, 1.27P
CASE 483AT
ISSUE B

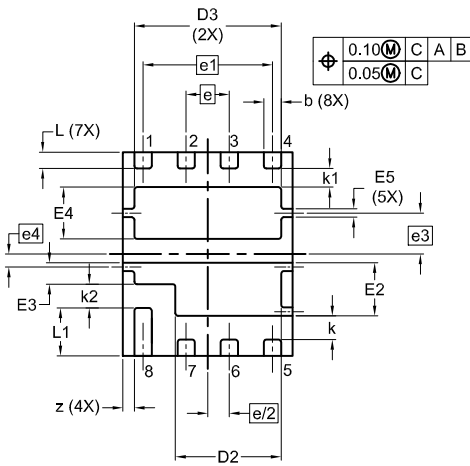
DATE 28 APR 2021



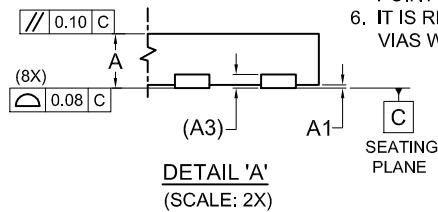
TOP VIEW



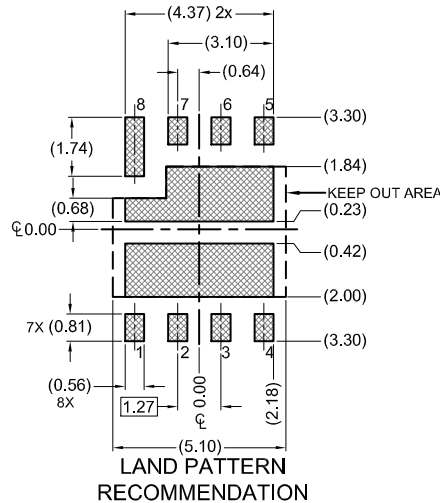
SIDE VIEW



BOTTOM VIEW



DETAIL 'A'
(SCALE: 2X)



LAND PATTERN
RECOMMENDATION

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
6. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A3	0.20 REF		
b	0.41	0.51	0.61
D	4.90	5.00	5.10
D2	3.01	3.11	3.21
D3	4.22	4.32	4.42
E	5.90	6.00	6.10
E2	1.47	1.57	1.67
E3	0.53	0.63	0.73
E4	1.42	1.52	1.62
E5	0.20	0.25	0.30
e	1.27 BSC		
e1	3.81 BSC		
e/2	0.64 BSC		
e3	1.08 BSC		
e4	0.25 BSC		
k	0.60	0.70	0.80
k1	0.45	0.55	0.65
k2	0.60	0.70	0.80
L	0.38	0.48	0.58
L1	1.31	1.41	1.51
z	0.34 REF		

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	PQFN8 5X6, 1.27P	PAGE 1 OF 1

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